

High Temperature X-ray Diffraction (HTXRD) Studies of Ceria Thin Films Prepared by Pulsed Laser Deposition

G. Balakrishnan^{1*}, P. Kuppusami² and D. Sastikumar³

¹Department of Nanotechnology, Bharath Institute of Science and Technology, Bharath Institute of Higher Education and Research, Chennai-600073, India

⁵Centre of Nanoscience and Nanotechnology, Sathyabama Institute of Science and Technology, Chennai-600119, India

³Department of Physics, National Institute of Technology, Tiruchirapalli-620 015, India.

Abstract

The ceria thin film was deposited on Si (100) at an optimized oxygen partial pressure of 3.0×10^{-2} mbar at room temperature. The thickness of the film was measured and it was found to be $\sim 1\mu\text{m}$. To examine the phase stability and thermal expansion behaviour of CeO_2 thin film, the high temperature x-ray diffraction (HTXRD) was employed in the temperature range RT-1273 K. The HTXRD pattern revealed that in all the temperatures (RT-1273 K), the film showed polycrystalline nature and having cubic phase. The HTXRD pattern showed excellent thermal stability in the temperature range of study. The lattice parameter and unit cell volume have been calculated as a function of temperature. The mean linear thermal expansion coefficient was calculated as a function of temperature and it was found to be $10.16 \times 10^{-6} \text{ K}^{-1}$ in the temperature range RT-1273 K.

Key words: Thin films, Cerium oxide, Pulsed laser deposition, High temperature x-ray diffraction, Mean linear thermal expansion coefficient.

*Corresponding author: balaphysics76@gmail.com

1. Introduction

Cerium oxide has high refractive index, high melting point, large dielectric constant, wide band gap, high transparency in the VIS-NIR regions, chemical stability and thermal stability [1,2]. Thorium is expected to play an important role in the third stage of the Indian nuclear reactor program [3]. A research on lattice thermal expansion behaviour of different thoria based systems is relevance to thorium oxide based nuclear reactors. Thermal expansion is an important parameter in the performance of a nuclear fuel-pin assembly. The main difficulties while investigating the PuO₂ based systems are its high radioactivity and toxicity which require extensive safety precautions. One way to overcome this problem is to use CeO₂ in place of PuO₂ as they have similar physico-chemical properties (ionic radii, melting points, enthalpy of formation, specific heat and thermal expansion coefficient etc.) Thus the plutonium chemistry can be well simulated using CeO₂ in place of highly active PuO₂ [4,5]. It is also a promising material for fast oxygen sensors at high temperature because of its chemical stability and high diffusion coefficient of oxygen vacancies. The coatings of rare earth oxides like, La₂O₃, CeO₂, Pr₂O₃ and Nb₂O₅ have lower thermal diffusivity, phase stability, high melting point, chemical inertness and high thermal expansion coefficient and hence they have potential as TBC materials [6].

In this work, thin films of CeO₂ were deposited on Si (100) substrates at room temperature and at an oxygen partial pressure of 3×10^{-2} mbar by pulsed laser deposition (PLD) using ceria target. PLD is a simple and unique technique [7] to prepare high quality thin films from a wide variety of materials and compounds. One of the main advantages of PLD is the generation of hyper thermal species with high kinetic energy of the order of 100 eV. Deposition of hyper thermal species can enhance the adatom

mobility and hence the film quality. High temperature x-ray diffraction (HTXRD) was employed to study the structural changes in the CeO₂ film as a function of temperature. HTXRD provides the information about variation of lattice parameters and hence average linear thermal expansion coefficients of the ceria thin films.

2. Experimental Procedures

Commercially available CeO₂ (99.99% purity) powder was compacted into a pellet of 25 mm diameter and 4 mm thickness at a pressure of 10 MPa using a uni-axial press. These pellets were sintered at 1673 K for 5 hours. The sintered pellet was used as a target for PLD. Prior to the deposition of CeO₂ thin films, the chamber was evacuated to 2×10^{-5} mbar using a turbo molecular pump backed with a rotary pump. The target was rotated and translated with an electric motor to avoid pitting on the target. The CeO₂ thin film was deposited on Si (100) substrates at an optimized oxygen partial pressure of 3×10^{-2} mbar at room temperature using the KrF excimer laser ($\lambda=248$ nm), energy density of 3 J/cm^2 and a repetition rate of 10 Hz. The thickness of the films was measured by the Dektak profilometer (DEKTAK 6M-stylus profiler by Veeco, USA). The structural changes of the deposited films were studied using INEL XRG – 3000 x-ray diffractometer (XRD) fitted with M/s Buehler high temperature (HT) camera HDK 2.4 and a curved position sensitive detector. The ceria thin film deposited on Si (100) substrate (of size 10mm x10mm) was placed over a tantalum strip, which served as a sample stage as well as heating element. A W-Re thermocouple was used for measuring the temperature of the sample. The XRD patterns were recorded in the temperature range RT -1273 K at the interval of 100 K in vacuum of the order of $\sim 2 \times 10^{-5}$ mbar. The heating rate of 10 K/min, cooling rate 25 K/min and soaking time of 5 minutes were followed. XRD patterns were recorded at set temperature for 30 minutes in parallel

recording mode. The unit-cell parameters were determined using a least-squares refinement program. The average linear thermal expansion coefficients were calculated in the temperature range 300 –1273 K.

3. Results and Discussion

The thickness of the films deposited was measured and it was found to be ~ 1 μm . The sintered ceria pellet was used as the target for thin film deposition. The XRD pattern of the pellet showed the phase pure CeO_2 having cubic structure ($a= 0.541 \text{ nm}$) (JCPDS No. 34-0394) [2]. HTXRD was employed on the ceria films in the temperature range of RT-1273 K to study the thermal stability and thermal expansion. Fig.1 shows the HTXRD patterns of the CeO_2 film and showed the peaks at an angle (2θ) of 28.55° , 33° , 47.4° , 56.3° , 59° , 69.4° , and 76.7° and these peaks are corresponding to the phase pure CeO_2 having cubic structure (JCPDS No. 34-0394). The peak intensity of (111), (200), (220) and (311) reflections were higher and the FWHM of these reflections decreased with the increase of temperatures.

The crystallite size was found to increase from 10 to 44 nm along (111) reflection, as the substrate temperature was raised from RT to 1273 K, and it increased from 21 to 98 nm along (200) orientation. The crystallite size has increased from 11 to 58 nm along (220) direction and it was 13-57 nm range along (311) reflection. Thus, it is seen that the crystalline growth was maximum along (200) orientation.

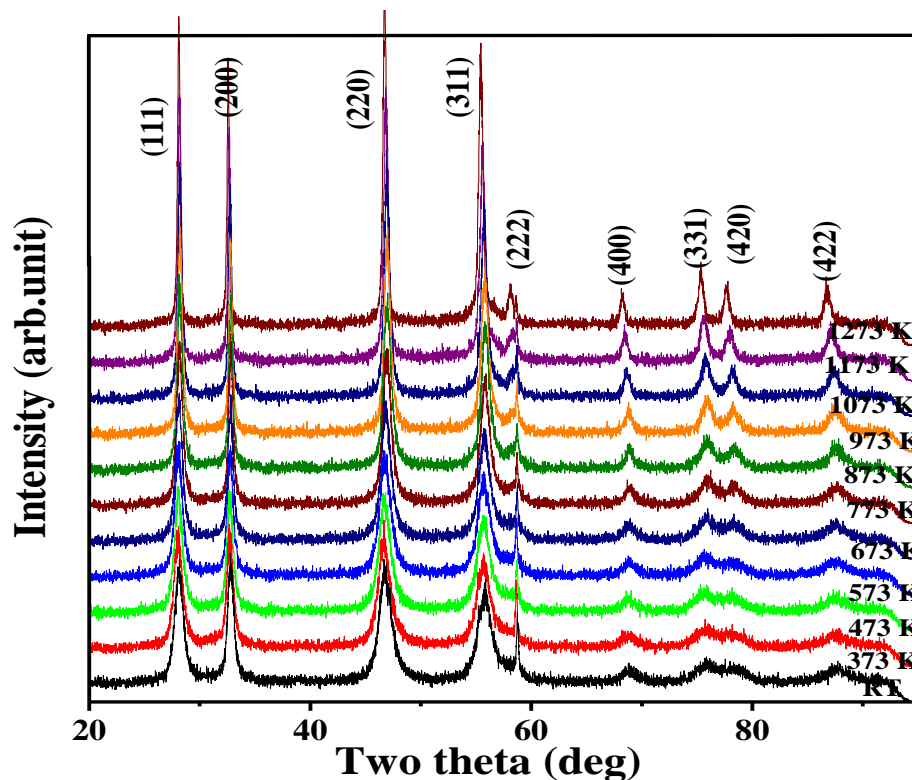


Fig.1. HTXRD profiles of the ceria thin film scanned in vacuum in the temperature range RT - 1273 K.

Lattice parameters were calculated as a function of temperature. The experimentally obtained lattice parameter data were fitted to third degree polynomial with temperature increment (T-300). The corrected lattice parameters were used for calculating thermal expansion coefficients.

$$a=5.446+7.07143 \times 10^{-5}(T-300)-8.38071 \times 10^{-8}(T-300)^2+4.49827 \times 10^{-11}(T-300)^3$$

The corrected lattice parameters for various temperatures are given in Table.1. The unit cell volume was also calculated using the corrected lattice parameters.

In cubic structure, the lattice parameter, a , was found to vary from 5.446 Å to 5.480 Å as the temperature was increased from RT to 1273 K. Once the lattice parameters are known as a function of temperature, it is possible to estimate the percent thermal expansion and mean linear thermal expansion coefficients.

The variation of percent linear thermal expansion along $a = \left(\frac{\Delta a}{a} \right) \times 100$ and percent volume (lattice) thermal expansion (v) with temperatures was calculated. The maximum linear thermal expansion of 0.6 % was observed at 1273 K and the maximum percent lattice thermal expansion (volume) was 2% at the same temperature. There was no phase change in the temperature range 300-1273K. Hence the film showed excellent thermal stability throughout the temperature range of study. The mean thermal expansion coefficient of the cubic phase ceria has been calculated using the following expression [8]:

$$\alpha_a = \frac{1}{a_{RT}} \left[\frac{a_T - a_{RT}}{T - RT} \right]$$

The mean linear thermal expansion coefficient and volume thermal expansion coefficients were calculated and are presented in Table.1. The mean linear thermal expansion is found to be $10.16 \times 10^{-6} \text{ K}^{-1}$ (298-1273 K). The mean volume thermal expansion coefficient is $30.51 \times 10^{-6} \text{ K}^{-1}$.

Table 1. Temperature versus lattice parameters and thermal expansion coefficients

Temperature (K)	a (corrected) (Å)	V (Å ³)	$\alpha_a \times 10^{-6}$ (K ⁻¹)	$\alpha_v \times 10^{-6}$ (K ⁻¹)
298	5.446	161.522	-----	-----
373	5.4543	162.262	20.95	62.759
473	5.4595	162.726	14.39	43.087
573	5.4635	163.084	11.82	35.423
673	5.4666	163.362	10.16	30.540
773	5.4690	163.577	8.95	26.897
873	5.4710	163.757	8.03	24.148
973	5.4729	163.927	7.35	22.124
1073	5.4749	164.107	6.88	20.703
1173	5.4773	164.323	6.60	19.864
1273	5.4804	164.602	6.51	19.597

It was reported that the thermal expansion coefficient of the pure ceria was found to be $10.9 \times 10^{-6} \text{ K}^{-1}$ in the temperature range 298-800 K [9]. Mathew et al [10] investigated the bulk and lattice thermal expansion studies on $\text{Th}_{1-x}\text{Ce}_x\text{O}_2$ ($x=0.0, 0.04, 0.08$ and 1.0) using dilatometry and HTXRD. The average linear thermal expansion coefficient of CeO_2 was found to $11.58 \times 10^{-6} \text{ K}^{-1}$ and $11.76 \times 10^{-6} \text{ K}^{-1}$ using dilatometry and HTXRD studies respectively [10]. The values obtained in the present study are in agreement with the other reported values [9,10]. Due to its excellent thermal stability and higher thermal expansion coefficient, the ceria films can be used for high temperature applications.

4. Conclusions

In the present study phase stability, crystallite size, lattice parameter changes and thermal expansion coefficient of ceria thin films deposited on (100) Si has been investigated using HTXRD in the temperature range RT-1273 K. The HTXRD revealed that the film contained ceria of cubic phase and showed excellent thermal stability in the entire range RT-1273 K. The crystallite sizes of the ceria along different reflections were calculated and the film preferred more along (200). The average linear thermal expansion coefficient and mean lattice thermal expansion coefficient was found to be $10.16 \times 10^{-6} \text{ K}^{-1}$ and $30.51 \times 10^{-6} \text{ K}^{-1}$ respectively.

REFERENCES

- [1] P. Patsalas, S. Logothetidis and C. Metaxa, *Appl. Phys. Lett.* **81** (2002) 466.
- [2] G. Balakrishnan, P. Kuppasami, T. N. Sairam, R. Thirumurugesan, E. Mohandas, and D. Sastikumar, *J. Nanosci. Nanotechnol.*, **9** (2009) 5421.

- [3] R. Chidambaram In: M. Srinivasan and I. Kimura, Editors, Proceedings of the Indo–Japan Seminar on Thoria Utilization, Bombay, Indian Nuclear Society, and Atomic Energy Society of Japan, Dec, 1990.
- [4] A. K. Tyagi, B. R. Ambekar and M. D. Mathews, *J. Alloys Compd*, **337** (2002) 277.
- [5] Y.W. Lee, H.S. Kim, S.H. Kim, C.Y. Young, S.H. Na, G. Ledergerber, P. Heimgarbner, M. Pouchon and M. Burghartz *J. Nucl. Mater.* **274** (1999) 7.
- [6] Cao, X. Q., R. Vassen and D. Stoever *J. Eur. Ceram. Soc.*, **24** (2004) 1.
- [7] D.B. Chrisey and G.B. Hubler (Eds), Pulsed Laser Deposition of Thin Films, Wiley, New York, 1994.
- [8] Mahesh Bhagwat and Veda Ramasamy, *Mater. Res. Bull.* **39** (2004) 1627.
- [9] Tetsuo Hisashige, Yasuhisa Yamamura and Toshihide Tsuji *J. Alloys. Compd*, **408-412** (2006) 1153.
- [10] Mathews, M. D., B. R. Ambekar and A. K. Tyagi, *J. Nucl. Mater.*, **280** (2000) 246.
- [11] S. R. Bishopa , J. J. Kima , N. Thompsona , D. Chena , Y. Kurua,b T. Stefanika and H. L. Tuller, ECS Transactions, **35** (2011) 1137.